

New Jersey Semi-Conductor Products, Inc.

20 STERN AVE.
SPRINGFIELD, NEW JERSEY 07081
U.S.A.

TELEPHONE: (973) 376-2922
(212) 227-6005
FAX: (973) 376-8960

Advance Information

The RF Sub-Micron MOSFET Line

RF Power Field Effect Transistors

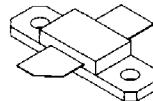
N-Channel Enhancement-Mode Lateral MOSFETs

Designed for PCN and PCS base station applications at frequencies from 1000 to 2600 MHz. Suitable for FM, TDMA, CDMA, and multicarrier amplifier applications. To be used in class A and class AB for PCN-PCS/cellular radio and wireless local loop.

- Specified Two-Tone Performance @ 2000 MHz, 26 Volts
 - Output Power = 30 Watts (PEP)
 - Power Gain = 10 dB
 - Efficiency = 30%
 - Intermodulation Distortion = -30 dBc
- Typical Single-Tone Performance at 2000 MHz, 26 Volts
 - Output Power = 30 Watts (CW)
 - Power Gain = 9 dB
 - Efficiency = 45%
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- S-Parameter Characterization at High Bias Levels
- Excellent Thermal Stability
- Capable of Handling 10:1 VSWR, @ 26 Vdc, 2000 MHz, 30 Watts (CW) Output Power
- Gold Metallization for Improved Reliability

MRF284 MRF284S

30 W, 2000 MHz, 26 V
LATERAL N-CHANNEL
BROADBAND
RF POWER MOSFETS



CASE 360B-01,
(MRF284)



CASE 360C-03,
(MRF284S)

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	65	Vdc
Gate-Source Voltage	V _{GS}	±20	Vdc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	87.5 0.5	Watts W/ ^o C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Operating Junction Temperature	T _J	200	°C

THERMAL CHARACTERISTICS

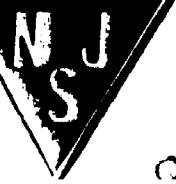
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R _{θJC}	2.0	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain-Source Breakdown Voltage (V _{GS} = 0, I _D = 10 μAdc)	V _{(BR)DSS}	65	—	—	Vdc
Zero Gate Voltage Drain Current (V _{DS} = 20 Vdc, V _{GS} = 0)	I _{DSS}	—	—	1.0	μAdc
Gate-Source Leakage Current (V _{GS} = 20 Vdc, V _{DS} = 0)	I _{GSS}	—	—	10	μAdc

NOTE – **CAUTION** – MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.

NJ Semi-Conductors reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by NJ Semi-Conductors is believed to be both accurate and reliable at the time of going to press. However, NJ Semi-Conductors assumes no responsibility for any errors or omissions discovered in its use. NJ Semi-Conductors encourages customers to verify that datasheets are current before placing orders.



Quality Semi-Conductors

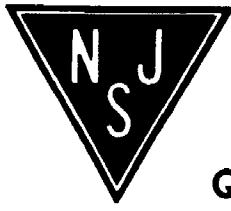
New Jersey Semi-Conductor Products, Inc.

20 STERN AVE.
SPRINGFIELD, NEW JERSEY 07081
U.S.A.

TELEPHONE: (973) 376-2922
(212) 227-6005
FAX: (973) 376-8960

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
ON CHARACTERISTICS					
Gate Threshold Voltage ($V_{DS} = 10 \text{ Vdc}$, $I_D = 150 \mu\text{Adc}$)	$V_{GS(\text{th})}$	2.0	3.0	4.0	Vdc
Gate Quiescent Voltage ($V_{DS} = 26 \text{ Vdc}$, $I_D = 200 \text{ mAdc}$)	$V_{GS(\text{q})}$	3.0	4.0	5.0	Vdc
Drain-Source On-Voltage ($V_{GS} = 10 \text{ Vdc}$, $I_D = 1.0 \text{ Adc}$)	$V_{DS(\text{on})}$	—	0.3	0.6	Vdc
Forward Transconductance ($V_{DS} = 10 \text{ Vdc}$, $I_D = 1.0 \text{ Adc}$)	g_{fs}	1.0	1.5	—	S
DYNAMIC CHARACTERISTICS					
Input Capacitance ($V_{DS} = 26 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$)	C_{iss}	—	37	—	pF
Output Capacitance ($V_{DS} = 26 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$)	C_{oss}	—	23	—	pF
Reverse Transfer Capacitance ($V_{DS} = 26 \text{ Vdc}$, $V_{GS} = 0$, $f = 1.0 \text{ MHz}$)	C_{rss}	—	1.2	—	pF
FUNCTIONAL TESTS (in Motorola Test Fixture)					
Common-Source Power Gain ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 2000.0 \text{ MHz}$, $f_2 = 2000.1 \text{ MHz}$)	G_{ps}	9	10.5	—	dB
Drain Efficiency ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 2000.0 \text{ MHz}$, $f_2 = 2000.1 \text{ MHz}$)	η	30	33	—	%
Intermodulation Distortion ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 2000.0 \text{ MHz}$, $f_2 = 2000.1 \text{ MHz}$)	I_{MD}	—	-33	-29	dBc
Input Return Loss ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 2000.0 \text{ MHz}$, $f_2 = 2000.1 \text{ MHz}$)	I_{RL}	9	24	—	dB
Common-Source Amplifier Power Gain ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W PEP}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 1930.0 \text{ MHz}$, $f_2 = 1930.1 \text{ MHz}$)	G_{ps}	9	10.7	—	dB
Drain Efficiency ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W PEP}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 1930.0 \text{ MHz}$, $f_2 = 1930.1 \text{ MHz}$)	η	—	33	—	%
Intermodulation Distortion ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W PEP}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 1930.0 \text{ MHz}$, $f_2 = 1930.1 \text{ MHz}$)	I_{MD}	—	-33	—	dBc
Input Return Loss ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W PEP}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 1930.0 \text{ MHz}$, $f_2 = 1930.1 \text{ MHz}$)	I_{RL}	9	15	—	dB
Common-Source Amplifier Power Gain ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W CW}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 2000.0 \text{ MHz}$)	G_{ps}	8.5	10.7	—	dB
Drain Efficiency ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W CW}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 2000.0 \text{ MHz}$)	η	35	—	—	%
Output Mismatch Stress ($V_{DD} = 26 \text{ Vdc}$, $P_{out} = 30 \text{ W CW}$, $I_{DQ} = 200 \text{ mA}$, $f_1 = 2000.0 \text{ MHz}$, $VSWR = 10:1$, at All Phase Angles)	Ψ	No Degradation In Output Power			



Quality Semi-Conductors